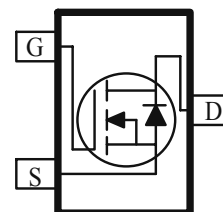
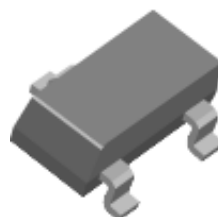


N-Channel 50-V (D-S) MOSFET

These miniature surface mount MOSFETs utilize High Cell Density process. Low $r_{DS(on)}$ assures minimal power loss and conserves energy, making this device ideal for use in power management circuitry. Typical applications are DC-DC converters, power management in portable and battery-powered products such as computers, printers, PCMCIA cards, cellular and cordless telephones.

- Low $r_{DS(on)}$ Provides Higher Efficiency and Extends Battery Life
- Miniature SOT-23 Surface Mount Package Saves Board Space

PRODUCT SUMMARY		
V_{DS} (V)	$r_{DS(on)}$ (Ω)	I_D (A)
50	3.5 @ $V_{GS} = 10V$	0.26
	6 @ $V_{GS} = 4.5V$	0.22
	10 @ $V_{GS} = 2.75V$	0.2



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)				
Parameter		Symbol	Maximum	Units
Drain-Source Voltage		V_{DS}	50	V
Gate-Source Voltage		V_{GS}	± 20	
Continuous Drain Current ^a	$T_A = 25^\circ\text{C}$	I_D	0.26	A
	$T_A = 70^\circ\text{C}$		0.2	
Pulsed Drain Current ^b		I_{DM}	0.9	
Continuous Source Current (Diode Conduction) ^a		I_S	0.2	A
Power Dissipation ^a	$T_A = 25^\circ\text{C}$	P_D	1.25	W
	$T_A = 70^\circ\text{C}$		0.8	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	-55 to 150	$^\circ\text{C}$

THERMAL RESISTANCE RATINGS				
Parameter		Symbol	Maximum	Units
Maximum Junction-to-Ambient ^a	$t \leq 5 \text{ sec}$	R_{THJA}	100	$^\circ\text{C/W}$
	Steady-State		166	

Notes

- Surface Mounted on 1" x 1" FR4 Board.
- Pulse width limited by maximum junction temperature

SPECIFICATIONS (T _A = 25°C UNLESS OTHERWISE NOTED)						
Parameter	Symbol	Test Conditions	Limits			Unit
			Min	Typ	Max	
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0 V, I _D = 250 uA	50			V
Gate-Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 uA	0.8	1.2	1.6	
Gate-Body Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = 8 V			100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 50 V, V _{GS} = 0 V			1	uA
		V _{DS} = 50 V, V _{GS} = 0 V, T _J = 55°C			10	
On-State Drain Current ^A	I _{D(on)}	V _{DS} = 5 V, V _{GS} = 4.5 V		0.2		A
Drain-Source On-Resistance ^A	r _{DS(on)}	V _{GS} = 2.75 V, I _D = 0.2 A			10	Ω
		V _{GS} = 4.5 V, I _D = 0.22 A		1.0	6.0	
		V _{GS} = 10 V, I _D = 0.26 A		0.7	3.5	
Forward Tranconductance ^A	g _{fs}	V _{DS} = 5 V, I _D = 1.5 A		7		S
Diode Forward Voltage	V _{SD}	I _S = 1.6 A, V _{GS} = 0 V		0.70	1.20	V
Dynamic ^b						
Total Gate Charge	Q _g	V _{DS} = 10 V, V _{GS} = 4.5 V, I _D = 1.7 A		3.5	5	nC
Gate-Source Charge	Q _{gs}			0.55		
Gate-Drain Charge	Q _{gd}			0.95		
Switching						
Turn-On Delay Time	t _{d(on)}	V _{DD} = 10 V, R _L = 6 Ω , R _G = 6 Ω, V _{GEN} = 4.5 V		5	15	ns
Rise Time	t _r			8	17	
Turn-Off Delay Time	t _{d(off)}			11	22	
Fall-Time	t _f			3	10	

Notes

- Pulse test: PW ≤ 300us duty cycle ≤ 2%.
- Guaranteed by design, not subject to production testing.

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Typical Electrical Characteristics

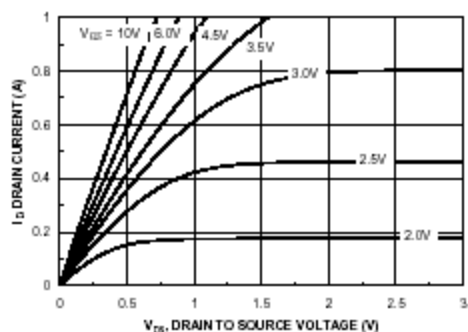


Figure 1. On-Region Characteristics.

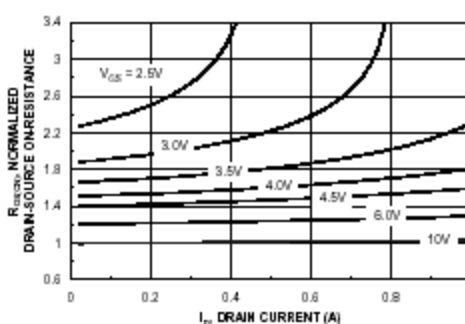


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

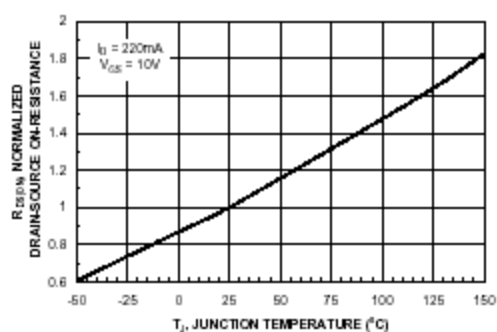


Figure 3. On-Resistance Variation with Temperature.

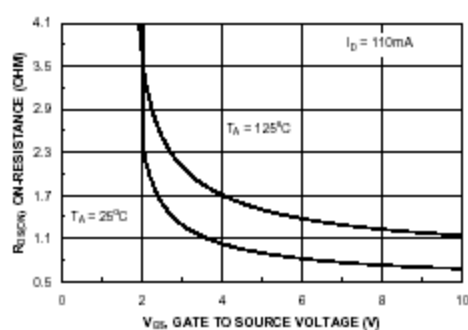


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

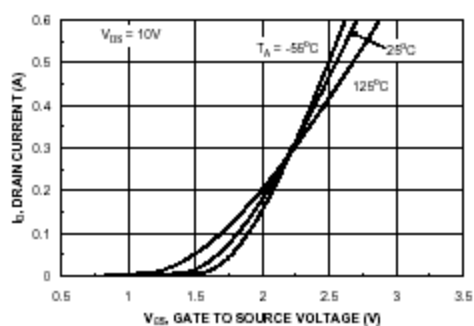


Figure 5. Transfer Characteristics.

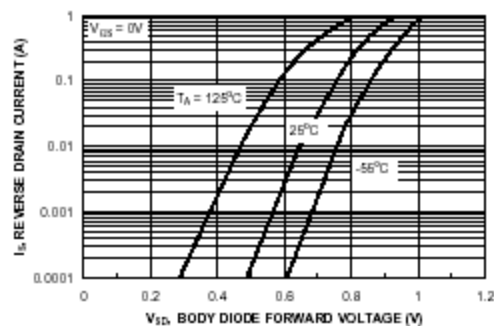


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Electrical Characteristics

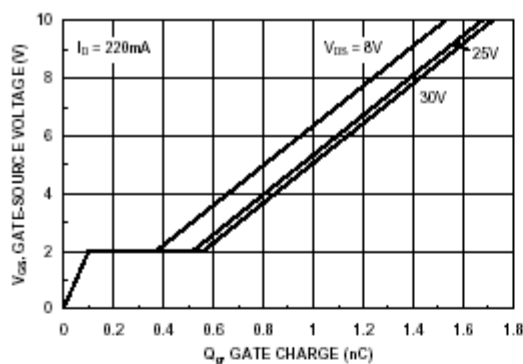


Figure 7. Gate Charge Characteristics.

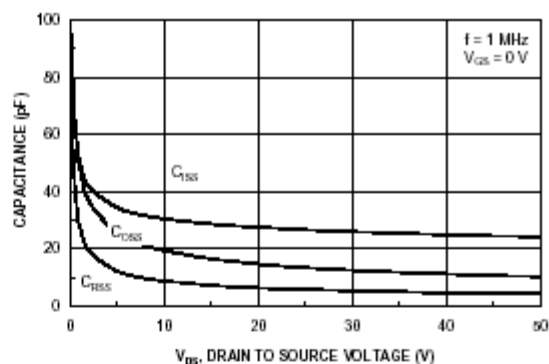


Figure 8. Capacitance Characteristics.

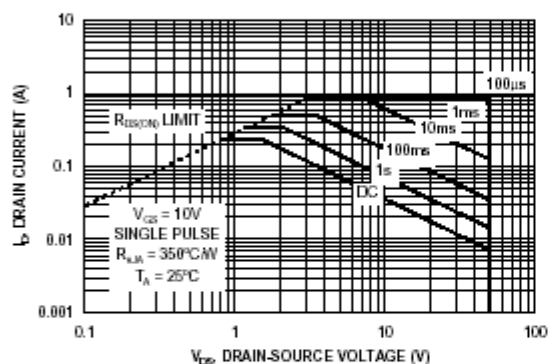


Figure 9. Maximum Safe Operating Area.

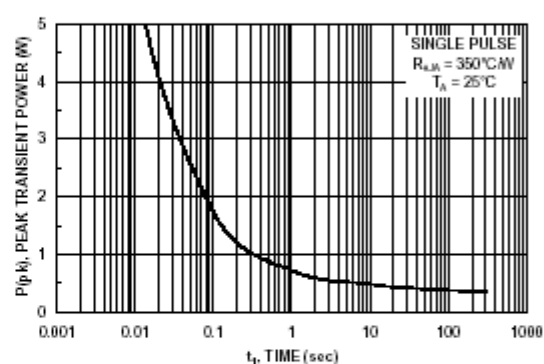


Figure 10. Single Pulse Maximum Power Dissipation.

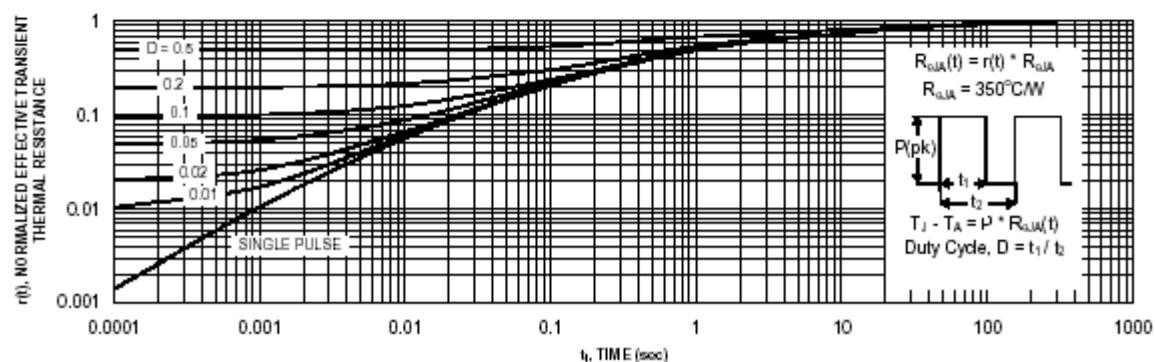
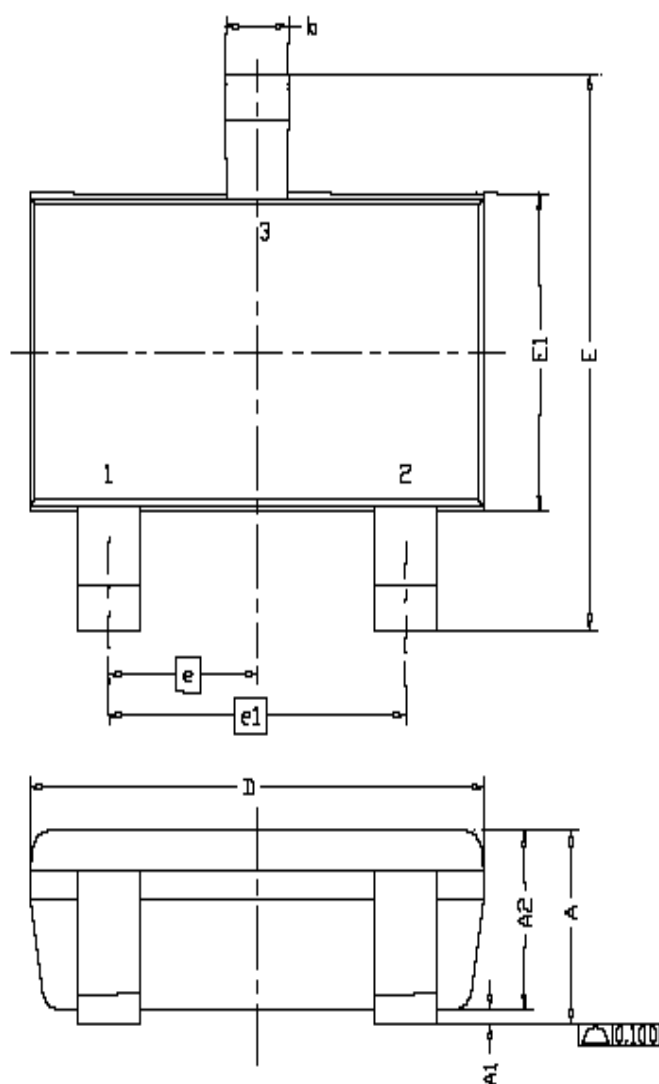


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1a.
Transient thermal response will change depending on the circuit board design.

Package Information



DIM.	MILLIMETERS		
	MIN	NOM	MAX
A	0.935	0.95	1.10
A1	0.01	---	0.10
A2	0.85	0.90	0.925
b	0.30	0.40	0.50
c	0.10	0.15	0.25
D	2.70	2.90	3.10
E	2.60	2.80	3.00
E1	1.40	1.60	1.80
e	0.95 BSC		
e1	1.90 BSC		
L	0.30	0.40	0.60
L1	0.60 REF		
L2	0.25 BSC		
R	0.10	---	---
θ	0°	4°	8°
$\theta1$	7° NOM		

